

87	77	(compar\$3 with (reference) with (pattern or die or circuit or image) with (difference or subtract\$4) with (select\$4 or choos\$4 or determin\$4)) and inspect\$4	USPAT; US-PGPUB	2002/04/12 17:06
90	5	die adj die adj inspection	USPAT; US-PGPUB	2002/04/12 17:06
93	107	die adj2 die with inspection	USPAT; US-PGPUB	2002/04/12 17:07
96	1	(die adj2 die with inspection) and (reference or template or model) near (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4) with image	USPAT; US-PGPUB	2002/04/12 17:08
99	16	(die adj2 die with inspection) and (reference or template or model) near (choos\$4 or determin\$4 or select\$4)	USPAT; US-PGPUB	2002/04/12 17:09

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L Number	Hits	Search Text	DB	Time stamp
1	609	(reference or template or model) near die	USPAT; US-PGPUB	2002/04/12 16:27
4	4	((reference or template or model) near die) same image near (difference or subtract\$4)	USPAT; US-PGPUB	2002/04/12 16:24
7	19	((reference or template or model) near die) with select\$4	USPAT; US-PGPUB	2002/04/12 16:00
10	11	((reference or template or model) near die) near2 (choos\$4 or determin\$4)	USPAT; US-PGPUB	2002/04/12 16:25
13	27	((reference or template or model) near die) with (defect\$4 or flaw)	USPAT; US-PGPUB	2002/04/12 16:04
16	14539	(reference or template or model) with (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4)	USPAT; US-PGPUB	2002/04/12 16:12
19	1403	(reference or template or model) near (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4)	USPAT; US-PGPUB	2002/04/12 16:13
25	4	((reference or template or model) near die) with subtract\$4	USPAT; US-PGPUB	2002/04/12 16:14
22	99	(reference or template or model) near (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4) with image	USPAT; US-PGPUB	2002/04/12 17:07
28	18	((reference or template or model) near (choos\$4 or determin\$4 or select\$4) with (difference or subtract\$4) with image) and inspect\$4	USPAT; US-PGPUB	2002/04/12 16:19
31	1	("4908871").PN.	USPAT; US-PGPUB	2002/04/12 16:21
34	2	select\$4 adj reference adj die	USPAT; US-PGPUB	2002/04/12 16:22
37	3	select\$4 adj reference adj die	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:23
42	1	2000-656045.NRAN.	DERWENT	2002/04/12 16:23
43	290	(reference or template or model) near die	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:24
48	1	((reference or template or model) near die) same image near (difference or subtract\$4)	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:24
53	8	((reference or template or model) near die) near2 (choos\$4 or determin\$4)	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:26
58	2	((reference or template or model) near die) and image with (difference or subtract\$4)	EPO; JPO; DERWENT; IBM_TDB	2002/04/12 16:27
63	1902	(382/141-154).CCLS.	USPAT; US-PGPUB	2002/04/12 16:27
66	20	(reference or template or model) near die and ((382/141-154).CCLS.)	USPAT; US-PGPUB	2002/04/12 16:31
69	166	reference adj die	USPAT; US-PGPUB	2002/04/12 16:40
72	6891	reference adj circuit	USPAT; US-PGPUB	2002/04/12 16:40
75	49	382/\$.ccls. and (reference adj circuit)	USPAT; US-PGPUB	2002/04/12 16:41
78	455	select\$4 with reference adj pattern	USPAT; US-PGPUB	2002/04/12 16:42
81	4	(select\$4 with reference adj pattern) with (difference or subtract\$4) with image	USPAT; US-PGPUB	2002/04/12 16:43
84	667	compar\$3 with (reference) with (pattern or die or circuit or image) with (difference or subtract\$4) with (select\$4 or choos\$4 or determin\$4)	USPAT; US-PGPUB	2002/04/12 16:46

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